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FMMT493

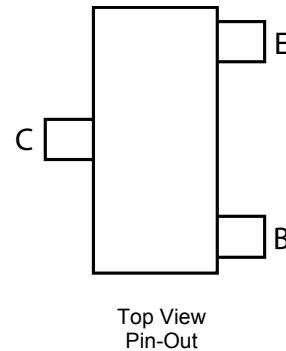
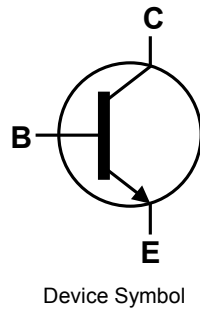
100V NPN MEDIUM POWER TRANSISTOR IN SOT23

Features

- $BV_{CEO} > 100V$
- $I_C = 1A$ High Continuous Collector Current
- $I_{CM} = 2A$ Peak Pulse Current
- 500mW Power Dissipation
- h_{FE} Characterised Up to 2A for High Current Gain Hold Up
- Complementary PNP Type: FMMT593
- **Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP capable (Note 4)**

Mechanical Data

- Case: SOT23
- Case material: Molded Plastic. "Green" Molding Compound.
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 $\text{\textcircled{3}}$
- Weight: 0.008 grams (Approximate)

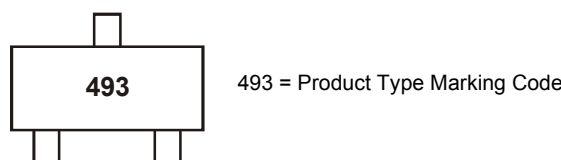


Ordering Information (Notes 4 & 5)

Part Number	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
FMMT493TA	AEC-Q101	493	7	8	3,000
FMMT493QTA	Automotive	493	7	8	3,000
FMMT493TC	AEC-Q101	493	13	8	10,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product_compliance_definitions/.
 5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CB0}	120	V
Collector-Emitter Voltage	V _{CEO}	100	V
Emitter-Base Voltage	V _{EBO}	7	V
Continuous Collector Current	I _C	1	A
Peak Pulse Current	I _{CM}	2	A
Base Current	I _B	200	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

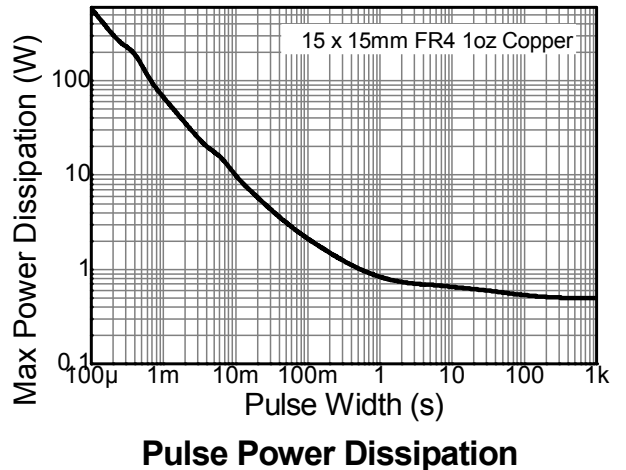
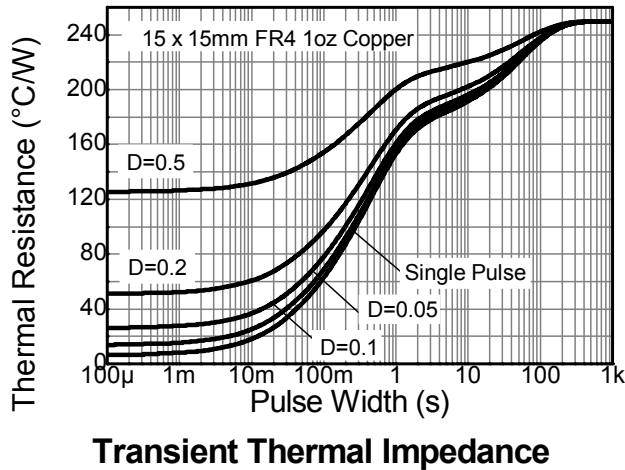
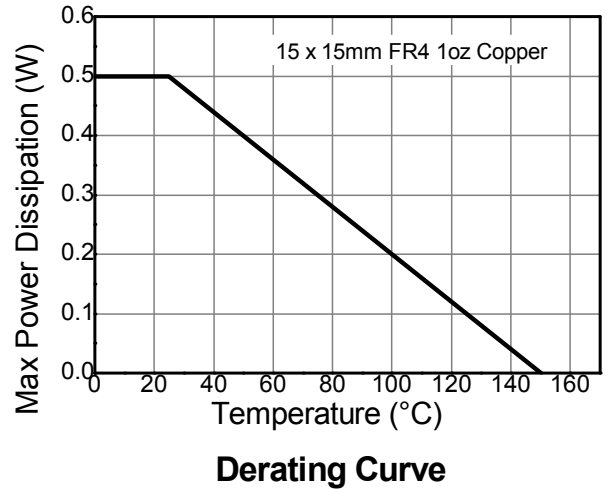
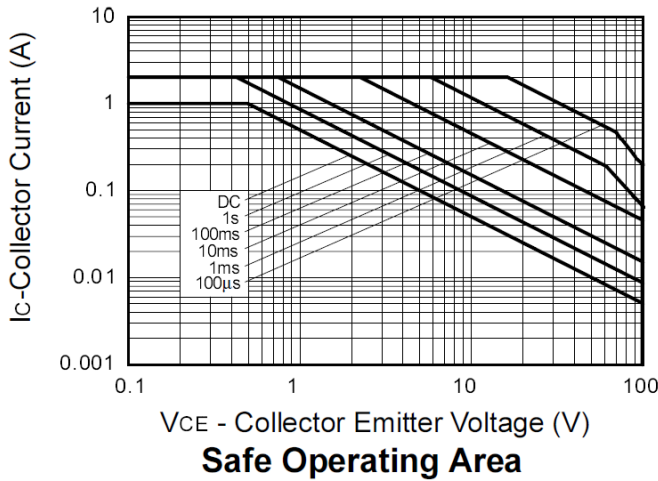
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	500	mW
Thermal Resistance, Junction to Ambient (Note 6)	R _{θJA}	250	°C/W
Thermal Resistance, Junction to Lead (Note 7)	R _{θJL}	197	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	≥ 400	V	C

- Notes:
- 6. For a device mounted on 15mm X 15mm 1oz weight copper that is on a single-sided FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
 - 7. Thermal resistance from junction to solder-point (at the end of the collector lead).
 - 8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information

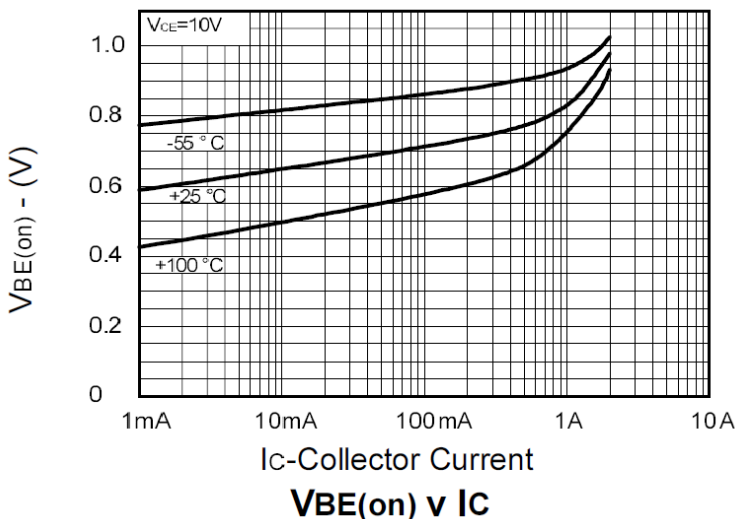
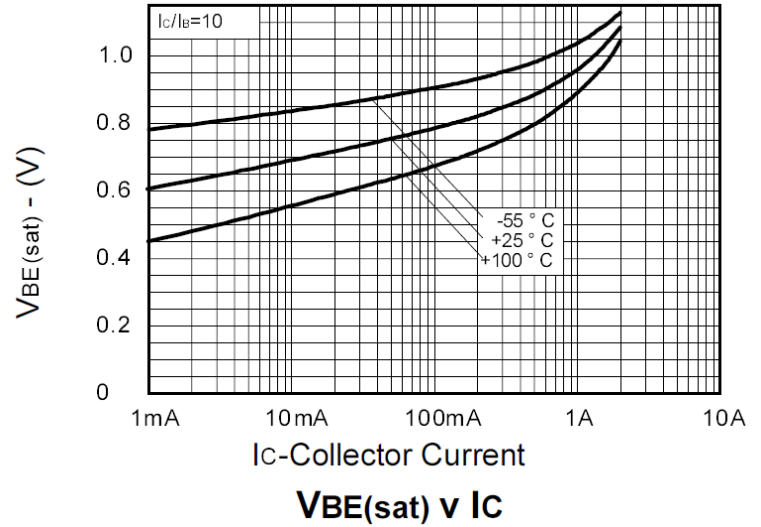
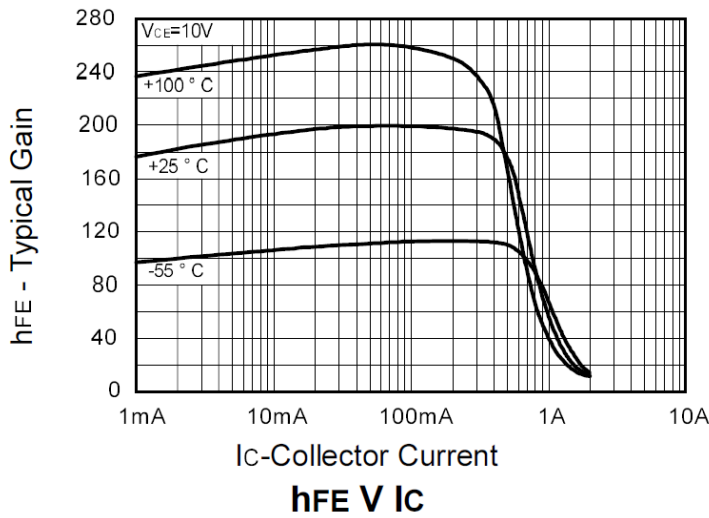
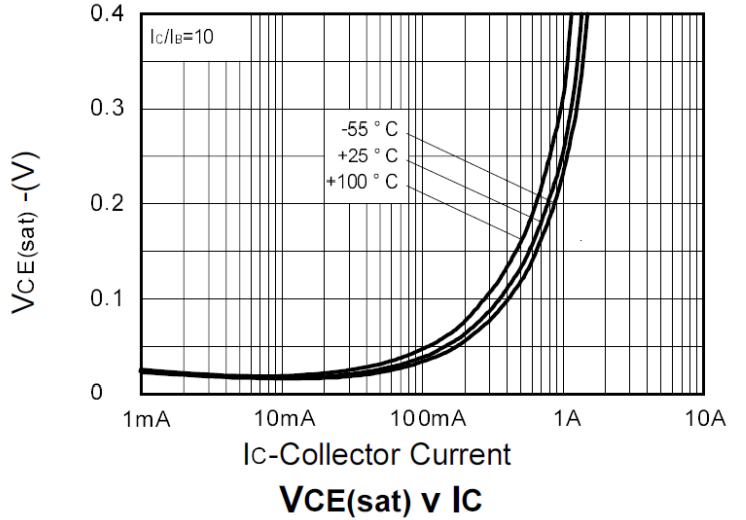
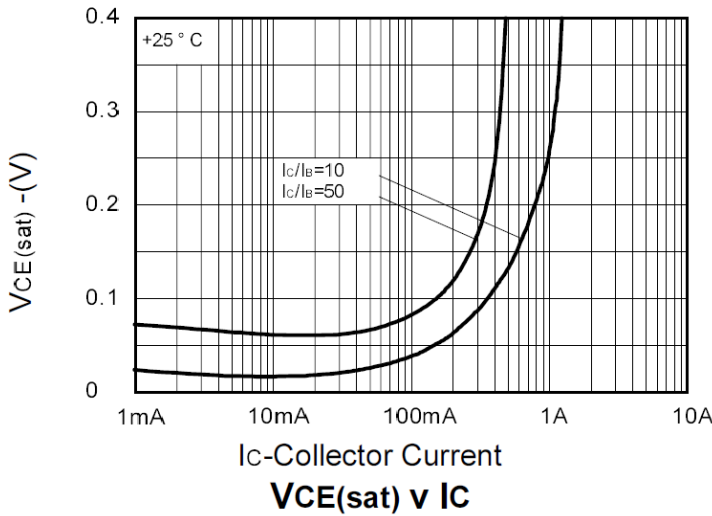


Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	120	—	—	V	I _C = 100μA
Collector-Emitter Breakdown Voltage (Note 9)	BV _{CEO}	100	—	—	V	I _C = 1mA
Emitter-Base Breakdown Voltage	BV _{EBO}	7	—	—	V	I _E = 100μA
Collector Cutoff Current	I _{CBO}	—	—	100	nA	V _{CB} = 100V
Emitter Cutoff Current	I _{EBO}	—	—	50	nA	V _{EB} = 5.6V
Collector Emitter Cutoff Current	I _{CES}	—	—	100	nA	V _{CE} = 100V
Static Forward Current Transfer Ratio (Note 9)	h _{FE}	100 100 60 20	— — — —	— 300 — —	—	I _C = 1mA, V _{CE} = 10V I _C = 250mA, V _{CE} = 10V I _C = 500mA, V _{CE} = 10V I _C = 1A, V _{CE} = 10V
Collector-Emitter Saturation Voltage (Note 9)	V _{CE(sat)}	—	—	300 600	mV mV	I _C = 500mA, I _B = 50mA I _C = 1A, I _B = 100mA
Base-Emitter Turn-On Voltage(Note 9)	V _{BE(on)}	—	—	1.0	V	I _C = 1A, V _{CE} = 10V
Base-Emitter Saturation Voltage(Note 9)	V _{BE(sat)}	—	—	1.15	V	I _C = 1A, I _B = 100mA
Output Capacitance	C _{obo}	—	—	10	pF	V _{CB} = 10V, f = 1MHz
Transition Frequency	f _T	150	—	—	MHz	V _{CE} = 10V, I _C = 50mA, f = 100MHz

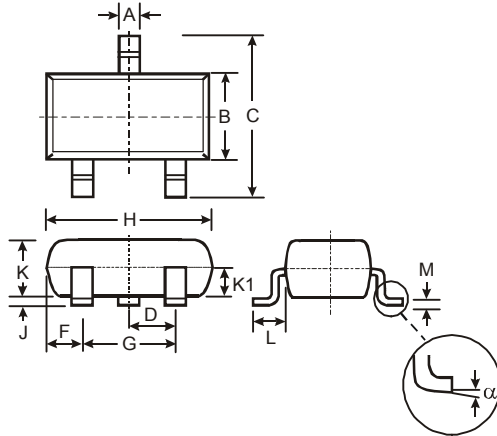
Note: 9. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)



Package Outline Dimensions

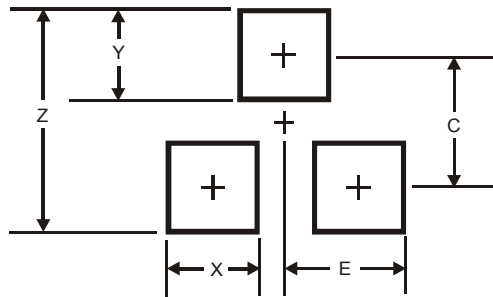
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.903	1.10	1.00
K1	-	-	0.400
L	0.45	0.61	0.55
M	0.085	0.18	0.11
α	0°	8°	-
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

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